



#### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T₄ = +25°C
	11.5mΩ @ V <sub>GS</sub> = 10V	11.6A
40V	18mΩ @ V <sub>GS</sub> = 4.5V	9.3A

### Description

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

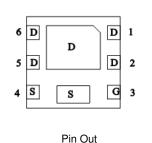
- Power Management Functions
- DC-DC Converters
- Backlighting

#### Features

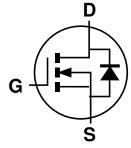
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Low R<sub>DS(ON)</sub> Ensures On State Losses Are Minimized
- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm<sup>2</sup>
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

### **Mechanical Data**

- Case: U-DFN2020-6 (SWP) (Type F)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.0065 grams (Approximate)



Bottom View



Internal Schematic

U-DFN2020-6 (SWP) (Type F)

Top View

Bottom View

## Ordering Information (Note 5)

Part Number	Case	Quantity Per Reel
DMTH4008LFDFWQ-7	U-DFN2020-6 (SWP) (Type F)	3,000
DMTH4008LFDFWQ-13	U-DFN2020-6 (SWP) (Type F)	10,000

No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

and Lead-free.

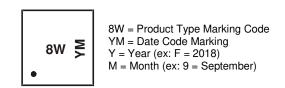
Notes:

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.

5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## **Marking Information**



Date Code Key												
Year	201	7	2018	2019	9	2020	202	1	2022	2023	3	2024
Code	E		F	G		Н	I		J	K		L
Month	Jan	Feb	Mar	Apr	May	/ Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DSS</sub>	40	V	
Gate-Source Voltage	V <sub>GSS</sub>	±20	V	
Continuous Drain Current (Note 7) $V_{GS}$ = 10V	Ι <sub>D</sub>	11.6 8.2	A	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		IDM	80	А
Continuous Source-Drain Diode Current (Note 7)	IS	2.55	А	
Pulsed Source-Drain Diode Current (10µs Pulse, Duty Cycle = 1%)	I <sub>SM</sub>	80	А	
Avalanche Current, L = 0.3mH (Note 8)	I <sub>AS</sub>	14.7	A	
Avalanche Energy, L = 0.3mH (Note 8)	E <sub>AS</sub>	32.4	mJ	

### **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	PD	0.99	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R <sub>0JA</sub>	153	°C/W
Total Power Dissipation (Note 7)	T <sub>A</sub> = +25°C	PD	2.35	W
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	R <sub>0JA</sub>	64.5	°C/W
Thermal Resistance, Junction to Case (Note 7)	T <sub>C</sub> = +25°C	R <sub>eJC</sub>	14.8	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

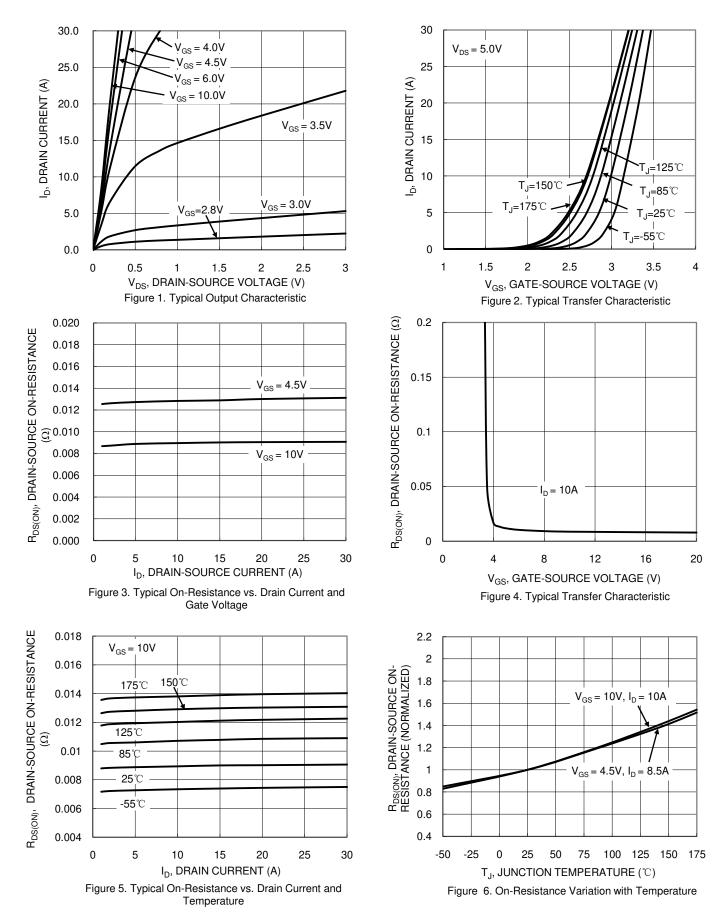
						-	
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	40	—	—	V	$V_{GS} = 0V, I_D = 250 \mu A$	
Zero Gate Voltage Drain Current	IDSS	—	—	1	μΑ	$V_{DS} = 32V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	1.7	3	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Resistance			9.1	11.5	mΩ	$V_{GS} = 10V, I_D = 10A$	
	R <sub>DS(ON)</sub>	_	12.9	18	11152	$V_{GS} = 4.5V, I_D = 8.5A$	
Diode Forward Voltage	V <sub>SD</sub>	_	0.8	1.0	V	$V_{GS} = 0V, I_{S} = 10A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	Ciss	—	1030	—			
Output Capacitance	Coss	—	324	—	pF	$V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	27	—			
Gate Resistance	Rg	_	1.82	—	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	—	6.8	—			
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	14.2	—	-0		
Gate-Source Charge	Q <sub>gs</sub>	_	2.0	—	nC	$V_{DD} = 20V, I_D = 10A$	
Gate-Drain Charge	Q <sub>qd</sub>	_	2.7	_			
Turn-On Delay Time	t <sub>D(ON)</sub>	_	3.1	—		$V_{DD} = 20V, V_{GS} = 10V,$	
Turn-On Rise Time	t <sub>R</sub>	_	3.1	_			
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	14.2	—	ns	$R_q = 6\Omega, I_D = 10A$	
Turn-Off Fall Time	tF	_	5.8	_	1	-	
Reverse Recovery Time	t <sub>RR</sub>	—	19.6	—	ns		
Reverse Recovery Charge	Q <sub>RR</sub>	—	8.2	—	nC	I <sub>F</sub> = 10A, di/dt = 100A/µs	

Notes: 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

bevice mounted on FR-4 substrate PC board, 202 copper, with minimum recommended pa 7. Device mounted on FR-4 substrate PC board, 202 copper, with 1inch square copper plate.
l<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> =+ 25°C.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing.



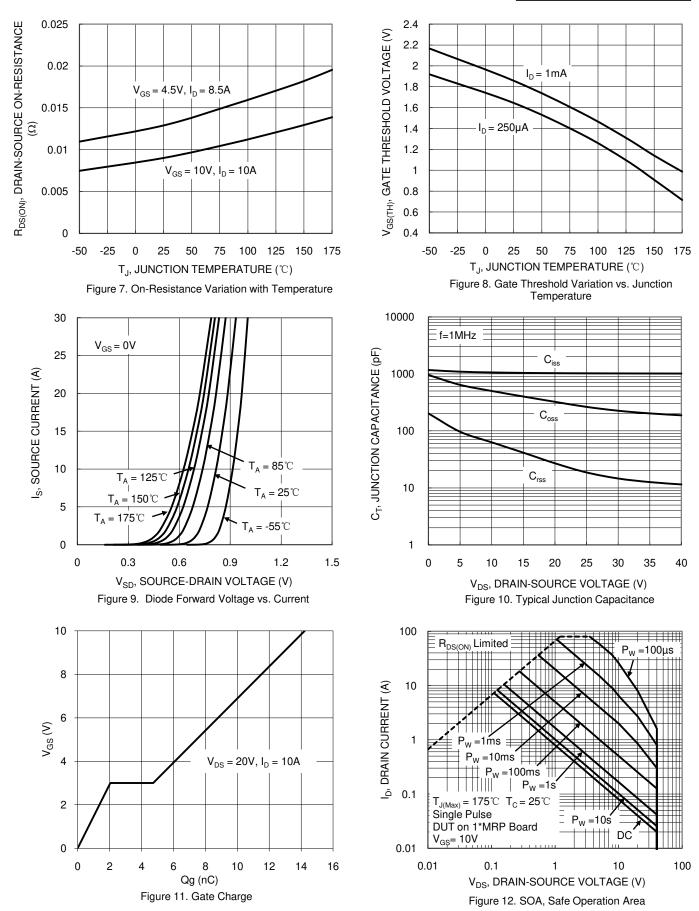
# DMTH4008LFDFWQ



DMTH4008LFDFWQ Datasheet number: DS39771 Rev. 3 - 2



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DMTH4008LFDFWQ Datasheet number: DS39771 Rev. 3 - 2



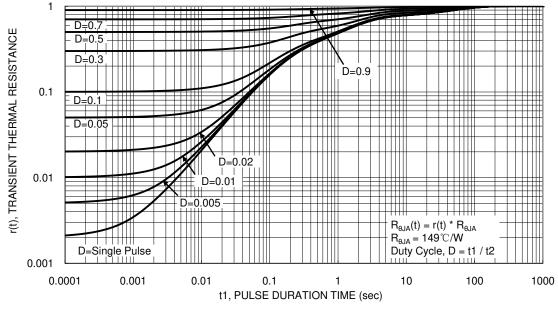
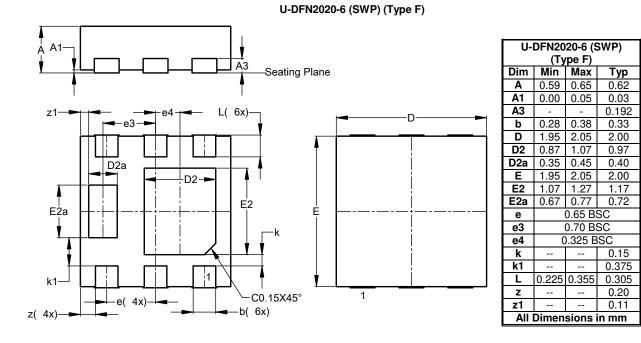


Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

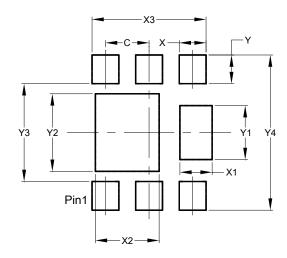
Please see http://www.diodes.com/package-outlines.html for the latest version.



# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (SWP) (Type F)



Dimensions	Value				
Dimensions	(in mm)				
С	0.650				
Х	0.400				
X1	0.480				
X2	0.950				
X3	1.700				
Y	0.425				
Y1	0.800				
Y2	1.150				
Y3	1.450				
Y4	2.300				



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